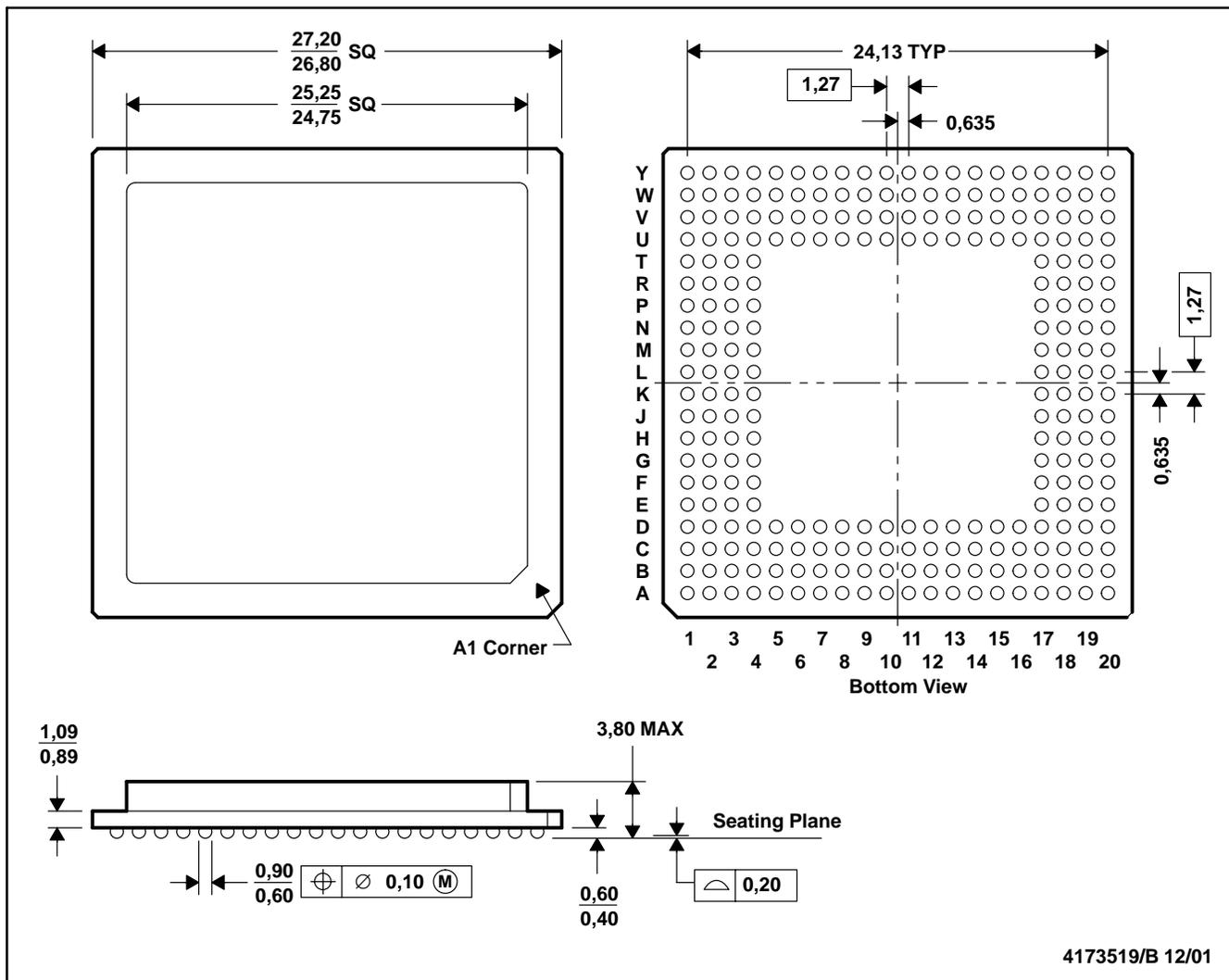


GHU (S-PBGA-N256)

PLASTIC BALL GRID ARRAY



4173519/B 12/01

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Thermally enhanced plastic package with heat slug (HSL)
  - D. Flip chip application only
  - E. Falls within JEDEC MO-151/BAR-2

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